

MULTIPLE-MILLING PROCESS FOR MANUFACTURING PRINTED CIRCUITS AND THE PRINTED CIRCUIT THUS OBTAINED

Abstract

A multiple-milling process for manufacturing printed circuits and the printed circuit thus obtained, constituted by a process for preparing the substrate of the printed circuit boards (1) for the production of bending areas (2) from whence to bend said printed circuits (1). This process consists of a multiple-milling system, by means of a mill (3) with special features, comprising a roll provided with multiple polishing strips on its surface, capable of making an undercutting in parallel strips (4) in said bending areas (2) of a printed circuit (1), allowing for their subsequent bending without deteriorating the metallic material conductive tracks adhered to the printed board's substrate on the side opposite the milled surface.